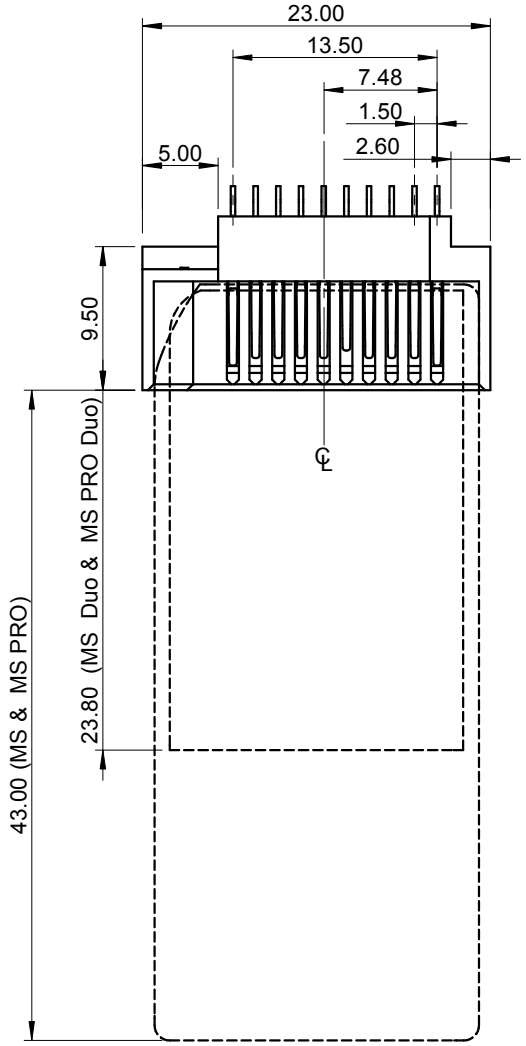
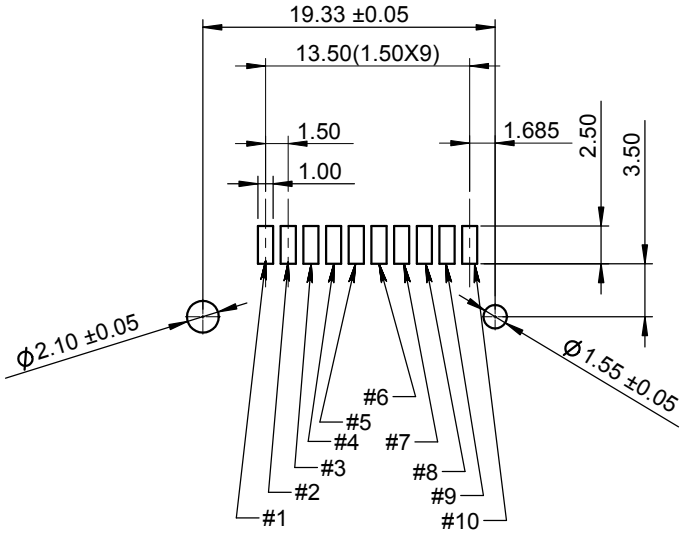
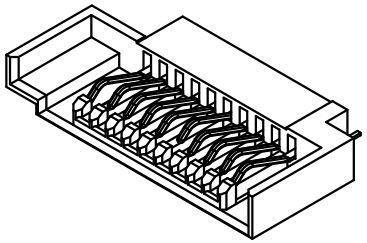
更改 REV	設 變 內 容 MODIFICATION
A	ECN01007



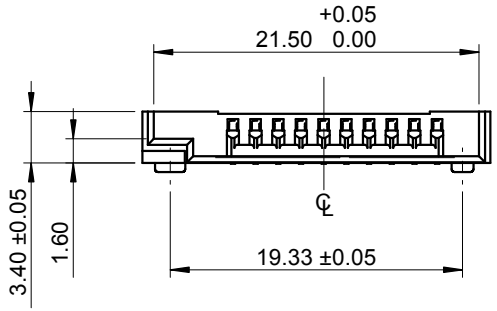


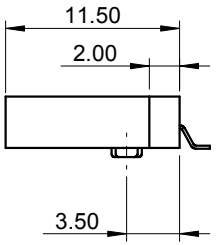
RECOMMEND PCB LAYOUT

NOTES :
1. MATERIAL :
   INSULATOR : HIGH TEMPRATURE THERMOPLASTIC, UL 94V-0,BLACK
   CONTACT : COPPER ALLOY
2.PLATING:
   CONTACT:10u"MIN.Au OVER 50u"MIN.NICKEL
   SOLDER TAIL:100u"min.Sn OVER NICKEL
3. PART NO : MSMS-B0-X002
   PACKING:
   0:TRAY
   1:REEL



PIN	DEFINITION
MS#1	VSS
MS#2	BS
MS#3	DATA1
MS#4	SDIO/DATA0
MS#5	DATA2
MS#6	INS
MS#7	DATA3
MS#8	SCLK
MS#9	VCC
MS#10	VSS





GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°
	.XXX°± 0.5°

KINGCONN 皇海科技股份有限公司

名 稱(TITLE): MS & MS PRO & MS Duo & MS PRO Duo CONNECTOR SIMPLE TYPE

單 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)
mm	MSMS-B0-X002	MSMS-B0-X002-A

審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 2:1	張數 SHEET 1/1
			角 法 PROJ.	更改 REV A